


IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

<p>In re application of: Ashjaee et al.</p> <p>Serial No.: Not yet assigned</p> <p>Filed: February 25, 2004</p> <p>Title: Method of Sealing Wafer Backside for Full-Face Processing (as amended)</p>	<p>Group Art Unit: Not yet assigned Examiner: Not yet assigned Docket: NT-216C1-US</p> <p>CERTIFICATE OF MAILING I hereby certify that this correspondence is being deposited with the US Postal Service as Express Mail Post Office to Addressee with Express Mailing Label No. <u>ER 619647606 US</u> to the address Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22213 on February 25, 2004.</p> <p>Signed:  Daniel Hopen</p>
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PRELIMINARY AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22213

Dear Sir:

Prior to examination of the above-identified application, please amend the application as follows:

Amendments to the Specification begins on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims, which begins on page 7 of this paper.

Remarks/Arguments begin on page 13 of this paper.